

**REMARKS**

Claims 1-18 are pending in the present application. Claims 1, 5 and 16-18 are independent claims.

**35 U.S.C. §102 Cho**

Claims 1-18 stand rejected under 35 U.S.C. §102(b) as being anticipated by Cho. Applicant respectfully traverses this art grounds of rejection.

Cho discloses a stacking type semiconductor chip package. Cho consistently refers to “a double faced adhesive insulating member 8” (see column 2, line 43 to column 3, line 38). Referring to Figure 2, the upper semiconductor chip 7 and the lower semiconductor chip 5 are attached to upper and lower sides of the inner lead 1, respectively, with adhesive insulating member 8. It is clear that the double sided adhesive insulating member 8 is the only type of adhesive disclosed by Cho.

Therefore, Cho cannot disclose or suggest “a second adhesive member” as recited in independent claims 1, 5, and 16-18 (Emphasis added).

As such, claims 2-4 and 6-15, dependent upon independent claims 1 and 5, respectively, are likewise allowable over Cho at least for the reasons given above with respect to independent claims 1 and 5.

Applicant respectfully requests that the Examiner withdraw this art grounds of rejection.

Reconsideration and allowance of all pending claims is respectfully requested.

**CONCLUSION**

In the event that any matters remain at issue in the application, the Examiner is invited to contact the undersigned at (703) 668-8000 in the Northern Virginia area, for the purpose of a telephonic interview.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 08-0750 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17; particularly, extension of time fees.

Very truly yours,

HARNESS, DICKEY & PIERCE, P.L.C.

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